

IN THE CLAIMS

1. (Currently Amended) A method for mounting a plurality of elements comprising:
~~separating a plurality of devices, which have been elements, which are two-dimensionally formed and arrayed at a first period on a substrate, into individual elements while keeping the first period as it is, wherein a two-dimensional array of more than one but not all of the elements in a given row are~~ is separated from the substrate;
handling the individually separated elements so as to re-array the elements at a second period having a value equivalent to a multiple of the first period; and
transferring the re-arrayed elements on a mounting board, wherein the elements are mounted to the mounting board at a period equivalent to the second period.
2. (Currently Amended) A method according to claim 1, wherein said handling comprises [[a]] discretely selecting the elements at a ~~second~~ period having a value equivalent to a multiple of the first period, wherein the multiple is an integer;
said transferring comprising transferring the selected elements on a portion of the mounting board, wherein the plurality of elements are transferred on the entire surface of the mounting board by repeating said discrete selecting of elements and said transferring of the selected elements.
3. (Previously Presented) A method according to claim 2, wherein said discrete selecting of elements is carried out by peeling only elements, which are selected from the plurality of elements having been separated from each other on the surface of the substrate with the first period thereof kept as it is, from the substrate by irradiating the selected elements with an energy beam emitted from the back surface of the substrate, and temporarily transferring the peeled elements on a temporary board, thereby re-arraying the peeled elements thereon; and
said transferring of the selected elements is carried out by finally transferring the elements temporarily transferred on the temporary board on the mounting board.
4. (Previously Presented) A method according to claim 1, wherein said element re-arraying step comprises:

fixing the individually separated elements on a support enlargeable by a set multiple while keeping the first period of the elements as it is; and

enlarging the support by the set multiple, thereby re-arraying the elements at a second period having a value equivalent to the first period multiplied by the set multiple.

5. (Currently Amended) A method for mounting a plurality of elements comprising: separating a plurality of elements, which are arrayed at a first period on a substrate, into individual elements while keeping the first period as it is, wherein more than one but not all of the elements in a given row are separated from the substrate;

handling the individually separated elements so as to re-array the elements at a second period having a value equivalent to a multiple of the first period; and

transferring the re-arrayed elements on a mounting board, wherein the elements are mounted to the mounting board at a period equivalent to the second period,

wherein said element re-arranging step comprises fixing the individually separated elements on a support enlargeable by a set multiple while keeping the first period of the elements as it is, and enlarging the support by the set multiple, thereby re-arraying the elements at a second period having a value equivalent to the first period multiplied by the set multiple, and

A method according to claim 4, wherein said fixing is carried out by fixing the individually separated elements on a film-like support deformable by said set multiple; and said enlarging is carried out by drawing the film-like support at said set multiple.

6. (Currently Amended) A method for mounting a plurality of elements comprising: separating a plurality of elements, which are arrayed at a first period on a substrate, into individual elements while keeping the first period as it is, wherein more than one but not all of the elements in a given row are separated from the substrate;

handling the individually separated elements so as to re-array the elements at a second period having a value equivalent to a multiple of the first period; and

transferring the re-arrayed elements on a mounting board, wherein the elements are mounted to the mounting board at a period equivalent to the second period,

wherein said element re-arraying step comprises fixing the individually separated elements on a support enlargeable by a set multiple while keeping the first period of the elements as it is, and enlarging the support by the set multiple, thereby re-arraying the elements at a second period having a value equivalent to the first period multiplied by the set multiple, and

~~A method according to claim 4, wherein said fixing is carried out by fixing the individually separated elements on a support previously, repeatedly folded so as to be developable at said set multiple;~~ and

 said enlarging is carried out by developing the support at said set multiple.

7. (Previously Presented) A method according to claim 1, wherein said separating is carried out by separating a plurality of elements in such a manner that the elements are two-dimensionally arrayed at a first period in the longitudinal and lateral directions; and

 said handling is carried out by one-dimensionally re-arraying the elements in one of the longitudinal and lateral direction, and then one-dimensionally re-arraying the elements in the other of the longitudinal and lateral directions.

8. (Previously Presented) A method according to claim 1, wherein said handling is carried out by performing a first re-array operation at a first magnification and then performing a second re-array operation at a second magnification, the product of the first magnification and the second magnification being equal to said specific magnification.

9. (Previously Presented) A method according to claim 1, wherein said separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements; and

 said transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.

10. (Cancelled)

11. (Currently Amended) A method for ~~mounting~~ separating a plurality of elements comprising:

separating a plurality of elements arrayed on a substrate from the substrate, wherein the elements have been two-dimensionally formed and arrayed on the substrate at a first period, and wherein more than one but not all of the elements in a given row are separated;

handling the ~~individually separated~~ elements so as to re-array the elements separated from the substrate at a second period equivalent to a multiple of the first period; and
transferring the re-arrayed elements on a mounting board.

12. (Previously Presented) A method according to claim 11, wherein the separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements, and wherein the transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.

13. (Currently Amended) A method for ~~mounting~~ separating a plurality of elements comprising:

separating a plurality of elements arrayed on a substrate from the substrate, wherein the elements have been two-dimensionally formed and arrayed on the substrate at a first period;

handling the ~~individually separated~~ elements so as to re-array the elements separated from the substrate at a second period equivalent to a multiple of the first period, wherein the multiple is an integer greater than one; and

transferring the re-arrayed elements on a mounting board.

14. (Previously Presented) A method according to claim 13, wherein the separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements, and wherein the transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.

15. (Currently Amended) A method for ~~mounting~~ separating a plurality of elements comprising:

separating a two-dimensional array of elements arrayed on a substrate from the substrate, wherein the elements have been two-dimensionally formed and arrayed on the substrate at a first period;

handling the ~~individually separated~~ elements so as to re-array the elements separated from the substrate at a second period equivalent to a multiple of the first period; and transferring the re-arrayed elements on a mounting board.

16. (Previously Presented) A method according to claim 15, wherein the multiple is an integer greater than one.

17. (Previously Presented) A method according to claim 15, wherein the separating is carried out by forming light emitting elements on a semiconductor substrate and separating the light emitting elements into individual light emitting elements, and wherein the transferring is carried out by transferring said light emitting elements at specific intervals on a mounting board of an image display.

18. (New) A method for mounting a plurality of elements comprising:

separating a two-dimensional array of elements from a substrate having a plurality of elements arrayed at a first period, wherein the individually separated elements are arrayed at a second period having a value equivalent to a multiple of the first period; and

transferring the separated two-dimensional array of elements on a mounting board, wherein the elements are mounted to the mounting board at a period equivalent to the second period.

19. (New) A method according to claim 18, wherein the elements are light emitting diodes.